X11SPM-TF



Embedded Ready VROC support

Key Features

- 1. 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors, , Single Socket LGA-3647 (Socket P) supported, CPU TDP support Up to 165W TDP
- 2. Intel® C622 chipset
- 3. Up to 1.5TB 3DS ECC RDIMM, DDR4-2933MHz; Up to 1.5TB 3DS ECC LRDIMM, DDR4-2933MHz, in 6 DIMM slots; Up to 1TB Intel Optane DC Persistent Memory in memory mode (Cascade Lake Only)
- 4. Expansion slots: 2 PCI-E 3.0 x16, 1 PCI-E 3.0 x8 (in x8)
- 5. M.2 NGFF connector

 M.2 Interface: PCI-E 3.0 x4
 Form Factor: 2242, 2280

Key: M-Key

- 6. 2 10GbE LAN ports
- 7. 12 SATA3 (6Gbps) via C622
- 8. Supports 12V DC power input
- 9. 5 USB 3.0 (2 rear, 1 Type-A, 2 via header), 6 USB 2.0 (2 rear, 4 via headers)
- 10. I/O: 1 VGA, 2 COM, TPM header

Specifications

Expansion Slots

PCI-E	■ 2 PCI-E 3.0 x16, ■ 1 PCI-E 3.0 x8
M.2	M.2 Interface: PCI-E 3.0 x4Form Factor: 2280, 2242Key: M-Key

System BIOS

BIOS Type	AMI UEFI
BIOS Features	ACPI 6.0RTC (Real Time Clock) WakeupSMBIOS 3.0 or later

Management

Software	 SuperDoctor® 5, NMI, <u>SUM</u>, KVM with dedicated LAN, <u>SPM</u>, Intel® Node Manager, <u>IPMI2.0</u>, Watchdog
Power	 Power-on mode for AC power
Configurations	recovery, ACPI Power Management

PC Health Monitoring

Voltage	 VBAT, Supports system management utility, Monitors CPU voltages, Chassis intrusion header, 3.3V standby, +5V standby, +5V, +3.3V, +12V, +1.8V, 8 -fan status
LED	UID/Remote UIDSuspend static indicator LEDCPU / System Overheat LED
Temperature	CPU thermal trip supportPECI
FAN	 8x 4-pin fan headers (up to 8 fans) System level control PWM fan speed control Fan speed control Overheat LED indication
Other Features	 WOL, UID, RoHS, M.2 NGFF connector, CPU thermal trip support for processor protection, Control of power-on for recovery from AC power loss, ACPI power management

Operating Environment

Operating Temperature Range	■ 0°C - 60°C (32°F - 140°F)
Non-Operating Temperature Range	■ -20°C - 60°C (-4°F - 140°F)

Product SKUs

MBD-X11SPM-
TC

X11SPM-TF

Physical Stats

Form Factor	■ microATX
Dimension	9.6" x 9.6" (24.38cm x 24.38cm)

Processor

CPU	 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors Single Socket LGA-3647 (Socket P) supported, CPU TDP supports Up to 165W TDP
Core	■ Up to 28 cores

System Memory

Memory Capacity	 6 DIMM slots Up to 1.5TB 3DS ECC LRDIMM, DDR4-2933MHz; Up to 1.5TB 3DS ECC RDIMM, DDR4-2933MHz
Memory Type	 2933/2666/2400/2133MHz ECC DDR4 LRDIMM (3DS), RDIMM (3DS)
DIMM Sizes	LRDIMM: 32GB, 64GB, 128GBRDIMM: 8GB, 16GB, 32GB, 64GB
Memory Voltage	■ 1.2V
Error Detection	■ Corrects single-bit errors

On-Board Devices

Chipset	■ Intel® C622
SATA	■ Intel® C622 controller for 12 SATA3 (6 Gbps) ports; RAID 0,1,5,10
IPMI	■ ASPEED AST2500
Graphics	■ ASPEED AST2500 BMC
Network Controllers	 Dual LAN with 10GBase-T with Intel® X722 + X557

Input / Output

SATA	■ 12 SATA3 (6Gbps) port(s)
LAN	■ 2 RJ45 10GBase-T ports
USB	 3 USB 3 port(s) (1 Type A; 2 via header) 6 USB 2.0 port(s) (4 via header; 2 rear) 2 USB 3.0 port(s) (2 rear)
Video Output	■ 1 VGA port(s)
Serial Port	2 COM Port(s) (1 header; 1 rear)
DOM	 2 SATA <u>DOM</u> (Disk on Module) power connector support
TPM	■ 1 TPM Header

Operating Relative Humidity Range	■ 10% - 85% (non-condensing)
Non Operating Relative Humidity Range	■ 10% - 95% (non-condensing)

Parts List

Parts List (Bulk Package)			
Name	Part Number	Qty	Description
Motherboard	MBD-X11SPM-TF	1	X11SPM-TF Motherboard
I/O Cables	CBL-0044L • €Store	2	57.5 cm SATA FLAT S-S PBF
I/O Shield	MCP-260-00109-0N • @Store	1	STD I/O Shield for X11SPM-TF with EMI Gasket

Parts List (Retail Packa	List (Retail Package)		
Name	Part Number	Qty	Description
Motherboard	MBD-X11SPM-TF	1	X11SPM-TF Motherboard
I/O Cables	CBL-0044L • €Store	4	57.5 cm SATA FLAT S-S PBF
I/O Shield	MCP-260-00109-0N • @Store	1	STD I/O Shield for X11SPM-TF with EMI Gasket
QRG	MNL-1939-QRG	1	Motherboard Quick Reference Guide

Optional Parts List				
Name	Part Number	Qty	Description	
1U I/O Shield	MCP-260-00114-0N		1U I/O Shield for X11SPM-TF with EMI Gasket	
TPM security module	AOM-TPM-9671V AOM-TPM-9670V		SPI capable TPM 1.2 with Infineon 9670 controller with vertical form factor SPI capable TPM 2.0 with Infineon 9670 controller with vertical form factor	

Chassis (Optimized for X11SPM-TF)

Embedded Compact	10	2U	3U	Mid/Mini- Tower	4U/Tower
	SC113MFAC2-	SC213LT-	SC833T-653B		SC842TQC-668B
	605CB	600LPB	Heatsink:SNK-		
	SC813MFTQC-	SC823TQ-	P0068APS4		
	R407CB	653LPB			
	SC515-R407	SC825TQC-			
	SC514-R407C	R740LPB			
	SC512F-350B1	SC825MBTQC-			
	SC813MFTQC-	R802LPB			
	350CB2	SC823MTQC-			
	SC515-350	R802LPB			
	SC113MFAC2-	SC213A-			
	R606CB	R740LPB			
	SC113MFAC2-	Heatsink:SNK-			
	341CB	P0068APS4			

 = Most optimized Chassis for SuperServer Configuration Blue color = Compatible Green color = Global SKU & Compatible Red dot & green color = Optimized + Global SKU

https://www.supermicro.com/en/products/motherboard/x11spm-tf